



ABSTRACT OF THE DISCLOSURE

5 A socket for a pin grid-array package includes a base housing having terminals arranged in the same grid pattern as the lead pins of the pin grid-array package and a cover mounted on the base housing for slidable movement relative to the base housing. The cover has through holes therein for receiving the lead pins of the pin grid-array package therethrough. The cover is movable relative to the base housing between a first, pin-insertion position and a second, contact-engagement. The cover and the base housing may include both metal and plastic components.